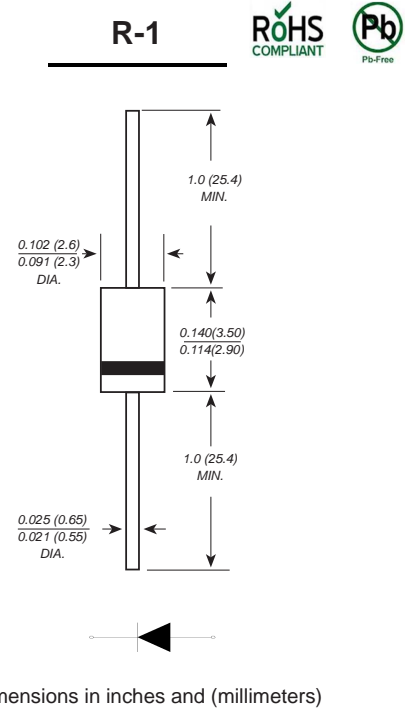


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 260°C/10 seconds at terminals

Mechanical Data

- Case** : Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0042 ounce, 0.12 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	1S1	1S2	1S3	1S4	1S5	1S6	1S7	1S8	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	150	200	300	400	500	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	350	420	V
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	500	600	V
Maximum average forward rectified current at T _L =100°C	I _(AV)	1.0								A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	30.0								A
Maximum instantaneous forward voltage at 1.0A	V _F	1.0			1.3		1.7			V
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =125°C	I _R	5.0				200				uA
Maximum reverse recovery time(Note 1)	T _{rr}	35								ns
Typical junction capacitance (Note2)	C _J	28.0								pF
Typical thermal resistance	R _{qJA}	65.0								°C/W
Operating junction and storage temperature range	T _J ,T _{STG}	-55 to +150								°C

Note: 1.Reverse recovery time test condition: I_F=0.5A I_R=1.0A I_{rr}=0.25A
 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

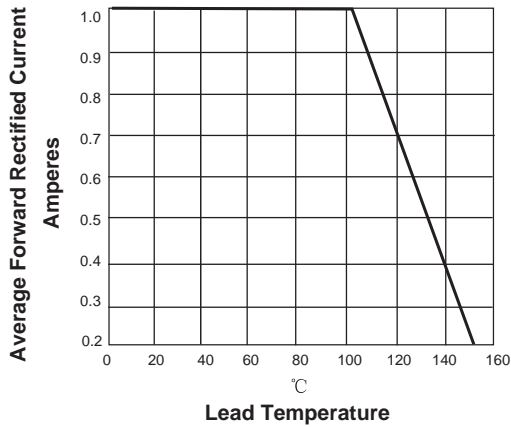


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

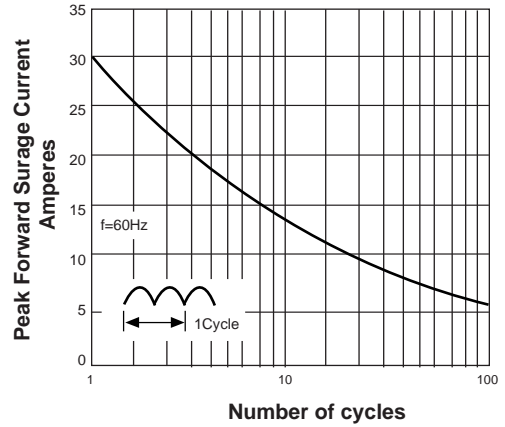


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

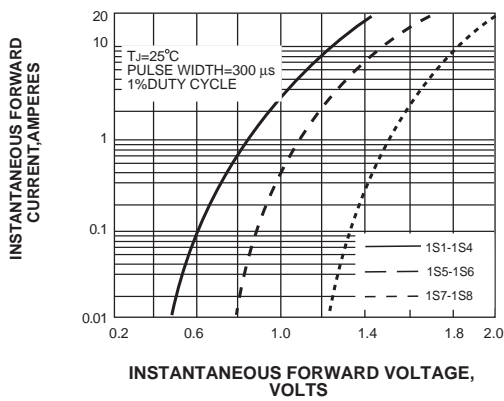
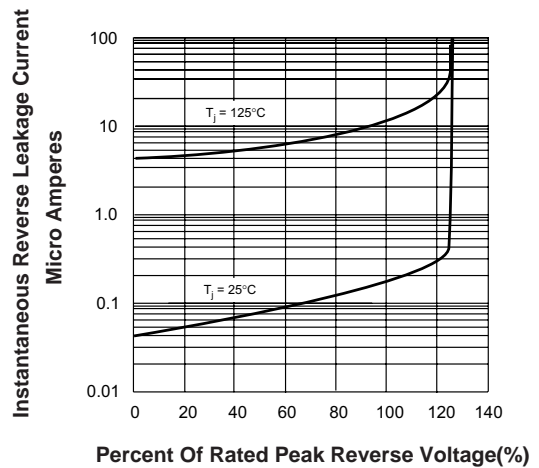
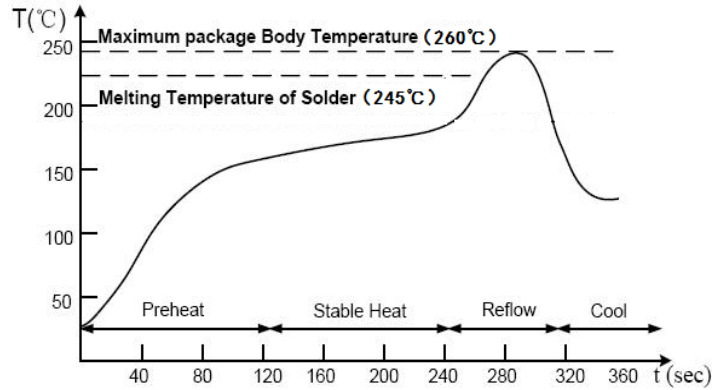


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile

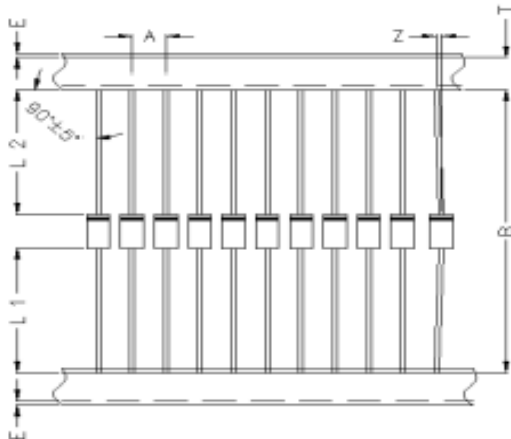


Note

- ◆ Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- ◆ The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- ◆ Devices can be cleaned using standard industry methods and solvents.
- ◆ If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Taping Specifications



Item	Symbol	Specifications(mm)
Component Pitch	A	5.0±0.5
Inner Tape Pitch	B	52.4±1.5
Component alignment	Z	1.2 Max
Tape width	T	6.0±0.5
Exposed adhesive	E	0.8 Max
Body eccentricity	L1-L2	1.0 Max

Ammunition Package Specifications

Package	Inner Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
R - 1	255*150*75	5	420*276*312	50